

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







1.8V/2.5V/3.3V, LVCMOS Peak EMI Reduction Clock Generator

Product Description

P3MS650100H device is a spread spectrum frequency modulator clock generator with 1.8 V/2.5 V/3.3 V LVCMOS output designed specifically for clock frequencies between 15 MHz and 60 MHz. P3MS650100H reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of all clock dependent signals. The device allows significant system cost savings by reducing the number of circuit board layers, ferrite beads, and shielding that are traditionally required to pass EMI regulations.

P3MS650100H accepts an LVCMOS input from an external reference clock and locks to a 1x modulated clock output. P3MS650100H goes to power down mode for power save when no clock is present on CLKIN pin. ModOUT goes 'low' in power down mode.

P3MS650100H operates over -20°C to +85°C and is available in a 4 Pin WDFN, (1.2mmX1.0mm) Package.

Features

- Peak EMI Reduction Clock Generator with LVCMOS Output
- Supply Voltage and Input / Output Clock Frequency Range

1.6 V – 2.0 V: 15 MHz – 30 MHz 2.3 V – 3.6 V: 15 MHz – 60 MHz

• Frequency Deviation: ±1.4% @ 24 MHz

• Power Down current less than 1 µA

• 4-pin WDFN (1.2mmX1.0mm) Package

• Output Drive Current: 1.8 V: 8 mA 2.5 V/3.3 V: 16 mA

- Operating temperature range: -20°C to +85°C
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

 P3MS650100H is targeted towards consumer electronic applications like mobile Phones, tablets, net books and MIDs

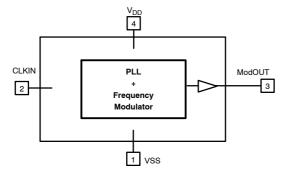


Figure 1. Simplified Block Diagram



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM

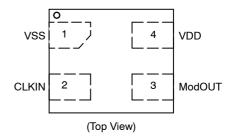


WDFN4 CASE 511BS



X = Specific Device CodeM = Date Code

PIN CONFIGURATION



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Table 1. PIN DESCRIPTION

Pin#	Pin Name	Туре	Description
1	VSS	Power	Ground connection.
2	CLKIN	Input	LVCMOS External reference clock input.
3	ModOUT	Output	Spread Spectrum Clock Output.
4	VDD	Power	Power supply for the entire chip

Table 2. OPERATING CONDITIONS

Symbol	Description	Min	Max	Unit
V _{DD} (1.8 V)	Supply Voltage with respect to V _{SS}	1.6	2.0	V
V _{DD} (2.5 V/3.3 V)		2.3	3.6	
T _A	Operating temperature	-20	+85	°C
C _L	Load Capacitance		15	pF
C _{IN}	Input Capacitance		5	pF

Table 3. ABSOLUTE MAXIMUM RATING

Symbol	Description	Rating	Unit
V_{DD}, V_{IN}	Voltage on any input pin with respect to V _{SS}	-0.5 to +4.6	V
T _{STG}	Storage temperature	-65 to +125	°C
T _s	Max. Soldering Temperature (10 sec)	260	°C
TJ	T _J Junction Temperature		°C
T _{DV}	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. DC Electrical Characteristics V_{DD} = 1.6 V - 2.0 V, $T_{A}{=}$ $-20^{\circ}C$ to $+85^{\circ}C$

Symbol	Parameter	Min	Тур	Max	Unit	
V_{DD}	Supply Voltage with respect to VSS		1.6	1.8	2.0	V
_	Dynamic supply current	15MHz		1.3	1.8	mΛ
I _{DD}	(Unloaded Output)	30MHz		2	2.8	mA
Icc	Static supply current (No Clock @ CLKIN)	Static supply current (No Clock @ CLKIN)			1	μΑ
V_{IH}	Input high voltage	0.65*VDD			V	
V_{IL}	Input low voltage			0.3*VDD	V	
I _{IH}	Input high current (CLKIN pin)			10	μΑ	
I _{IL}	Input low current (CLKIN pin)			10	μΑ	
V _{OH}	Output high voltage, I _{OH} = - 8mA	0.75*VDD			V	
V _{OL}	Output low voltage , I _{OL} = 8mA			0.2*VDD	V	
Z _{OUT}	Output impedance			28		Ω

Table 5. AC ELECTRICAL CHARACTERISTICS V_{DD} = 1.6 V - 2.0 V, T_{A} = $-20^{\circ}C$ to $+85^{\circ}C$

Symbol	Parameter			Тур	Max	Unit
CLKIN	Input Clock frequency		15		30	MHz
ModOUT	Output Clock frequency		15		30	MHz
t _{LH} (Notes 1 and 2)	Output rise time (Measured between 20% to 80%)			1.7	2.7	nS
t _{HL} (Notes 1 and 2)	Output fall time (Measured between 80% to 20%)			1.4	2.4	nS
t _{JC} (Notes 2)	Cycle-to-cycle Jitter, Peak (1000 cycles)	15 MHz		400		
		24 MHz		250		pS
	30		1			
t _D (Notes 1 and 2)	Output duty cycle (Measured @ 50%)			50	55	%
t _{ON} (Notes 1 and 2)	PLL lock Time (Stable power supply, valid clock presented on CLKIN)				3	mS
fd	Frequency Deviation @ 24 MHz			±1.4	±1.55	%

All parameters are specified with 15 pF loaded output.
 Parameter is guaranteed by design and characterization. Not 100% tested in production

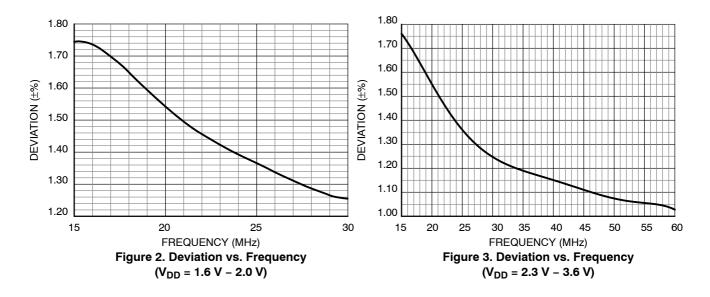
Table 6. DC ELECTRICAL CHARACTERISTICS V_{DD} = 2.3 V - 3.6 V, T_A = $-20^{\circ}C$ to $+85^{\circ}C$

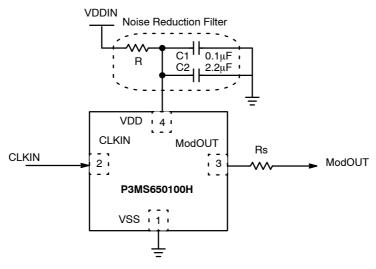
Symbol	Parameter	Min	Тур	Max	Unit	
V_{DD}	Supply Voltage with respect to VSS	2.3	2.8	3.6	V	
		15MHz		1.7	3	
I_{DD}	Dynamic supply current (Unloaded Output)	30MHz		2.8	5	mA
	(Onloaded Output)			5	9	
I _{CC}	Static supply current (No Clock @ CLKIN)			2	μΑ	
V _{IH}	Input high voltage	0.65 * V _{DD}			V	
V_{IL}	Input low voltage			0.3 * V _{DD}	V	
I _{IH}	Input high current (CLKIN pin)			10	μΑ	
I _{IL}	Input low current (CLKIN pin)			10	μΑ	
V _{OH}	Output high voltage, I _{OH} = −16 mA	0.75 * V _{DD}			V	
V _{OL}	Output low voltage, I _{OL} = 16 mA			0.2 * V _{DD}	V	
Z _{OUT}	Output impedance			20		Ω

Table 7. AC ELECTRICAL CHARACTERISTICS V_{DD} = $2.3~V-3.6~V,\,T_{A}$ = $-20^{\circ}C$ to $+85^{\circ}C$

Symbol	Parameter			Тур	Max	Unit
CLKIN	Input Clock frequency				60	MHz
ModOUT	Output Clock frequency		15		60	MHz
t _{LH} (Notes 3 and 4)	Output rise time (Measured between 20% to 80%)			0.8	1.6	nS
t _{HL} (Notes 3 and 4)	Output fall time (Measured between 80% to 20%)			0.8	1.6	nS
t _{JC} (Notes 4)	Cycle-to-cycle Jitter, Peak	15 MHz		350		pS
	(1000 cycles)	24 MHz		250		
		60 MHz		100		
t _D (Notes 3 and 4)	Output duty cycle			50	55	%
t _{ON} (Notes 3 and 4)	PLL lock Time (Stable power supply, valid clock presented on CLKIN)				3	mS
fd	Frequency Deviation @ 24 MHz			±1.4	±1.55	%

^{3.} All parameters are specified with 15 pF loaded output.4. Parameter is guaranteed by design and characterization. Not 100% tested in production





Rs = Trace Impedance of PCB – Output Impedance of Device (Z0) Note: Refer Pin Description table for Functionality details

Figure 4. Typical Application Schematic

PCB Layout Recommendation

For optimum device performance, following guidelines are recommended.

- ◆ Dedicated V_{DD} and GND planes.
- The device must be isolated from system power supply noise. A 0.1µF and a 2.2 µF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between the decoupling capacitor and VDD pin. The PCB trace to VDD pin and the ground via should be kept as short as possible. All the VDD pins should have decoupling capacitors.
- In an optimum layout all components are on the same side of the board, minimizing vias through other signal layers.

A typical layout is shown in the figure below.

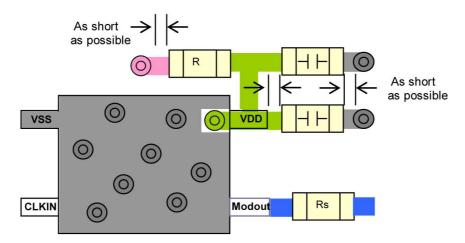


Figure 5. Recommended PCB Layout

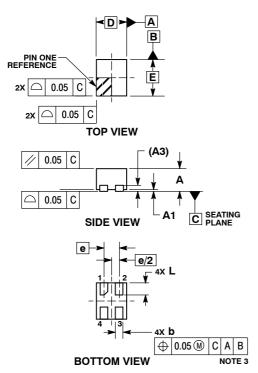
ORDERING INFORMATION

Ordering Code	Marking	Temperature	Package Type	Shipping [†]
P3MS650100H-4CR	Α	–20°C to +85°C	4-pin (1.2 mm x 1.0 mm) WDFN (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-Free.

PACKAGE DIMENSIONS

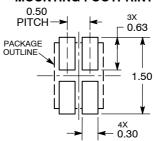
WDFN4, 1.0x1.2, 0.5P CASE 511BS-01 ISSUE O



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS
- PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS				
DIM	MIN	MAX			
Α	0.70	0.80			
A1	0.00	0.05			
А3	0.20 REF				
b	0.20	0.30			
D	1.00	BSC			
Е	1.20	BSC			
е	0.50 BSC				
L	0.35	0.45			

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and war engineer trademarks of semiconductor components industries, Ite (SciLLC) solitate services are injective to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative